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RESPONSE UNDER 37 CFR 1.116  
EXPEDITED PROCEDURE  
EXAMINING GROUP 1700

PATENT  
Attorney Docket No. 98124X205487  
Client Reference No. 98124

#19  
3/19/03  
NS

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

In re Application of:

Wang et al.

Application No. 09/636,161

Filed: August 10, 2000

For: POLISHING SYSTEM AND METHOD  
OF ITS USE

Art Unit: 1765

Examiner: Lynette T. Umez-Eronini

RESPONSE TO OFFICE ACTION

Commissioner for Patents  
Box AF  
Washington, D.C. 20231

Dear Sir:

In response to the Office Action dated January 14, 2003, please consider the following remarks.

REMARKS

*The Present Invention*

The present invention relates to a polishing system and composition for use in polishing a substrate, particularly a multi-layer substrate that includes a first metal layer and a second layer. Claims 1-6, 8, 9, 16-27, and 32-35 currently are pending. However, claim 2 has been withdrawn from consideration by the Office as being directed to a non-elected species.

*Summary of Examiner Interview*

Applicants thank Examiner Umez-Eronini for the courtesies extended to applicants' representatives, John Kilyk, Jr. and Robert M. Lanning, during the telephonic interview of February 25, 2003. The Section 103 rejection was discussed, consistent with the remarks set forth herein.